



VMDSEMI

VUDE003R086PA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
-30V	8.6mΩ@-10V	-40A
	13mΩ@-4.5V	

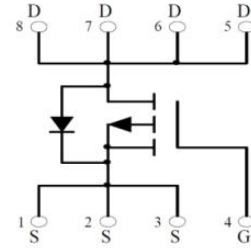
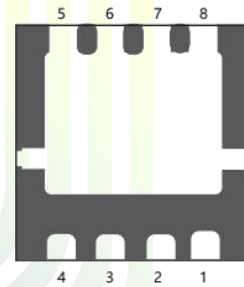


Figure 1 Symbol of VUDE003R086PA

Features

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Package Type



DFN3.3X3.3-8L

Application

- Power Switching Application
- Load switch

Figure 2 Package Type of VUDE003R086PA

Ordering Information

Product Name	Package
VUDE003R086PA	DFN3.3X3.3-8L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DSS}	-30	V	
Gate-Source Voltage	V_{GSS}	± 25	V	
Continuous Drain Current ^{Note1}	I_D	$T_C = 25\text{ °C}$	A	
Continuous Drain Current ^{Note1}		$T_C = 100\text{ °C}$		
Pulsed Drain Current ^{Note2}	I_{DM}	-128		
Single Pulsed Avalanche Current ^{Note3}	I_{AS}	-28		
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	196	mJ	
Total Power Dissipation ^{Note5}	P_D	$T_C = 25\text{ °C}$	96	W
Junction Temperature	T_J		150	°C
Storage Temperature	T_{STG}		-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		75		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1.3		°C/W



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-24V, V_{GS}=0V$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note3}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.5	-3.0	V
Static Drain-Source On-Resistance ^{Note3}	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-5A$		6.8	8.6	mΩ
		$V_{GS}=-4.5V, I_D=-5A$		8.5	13	
Forward Transconductance ^{Note3}	g_{FS}	$V_{DS}=-10V, I_D=-5A$	10			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=-15V$		3840		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		464		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		441		pF
Total Gate Charge	Q_g	$V_{DS}=-15V$		60		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=-10V$		15		
Gate-Drain Charge	Q_{gd}	$I_D=-10A$		18		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		5.0		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V$		25		ns
Turn-on Rise Time	t_r	$V_{GS}=-10V$		11		
Turn-off Delay Time	$t_{d(off)}$	$R_L=3\Omega$		136		
Turn-off Fall Time	t_f	$R_G=3\Omega$		49		
Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{SD}	$V_{GS}=0V, I_S=-5A$			-1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD}=-15V, V_{GS}=-10V, L=0.5mH, R_G=25\Omega$ Starting $T_J=25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)}=150^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz Copper, in a still air environment with $T_A=25^\circ C$.

Typical Performance Characteristics

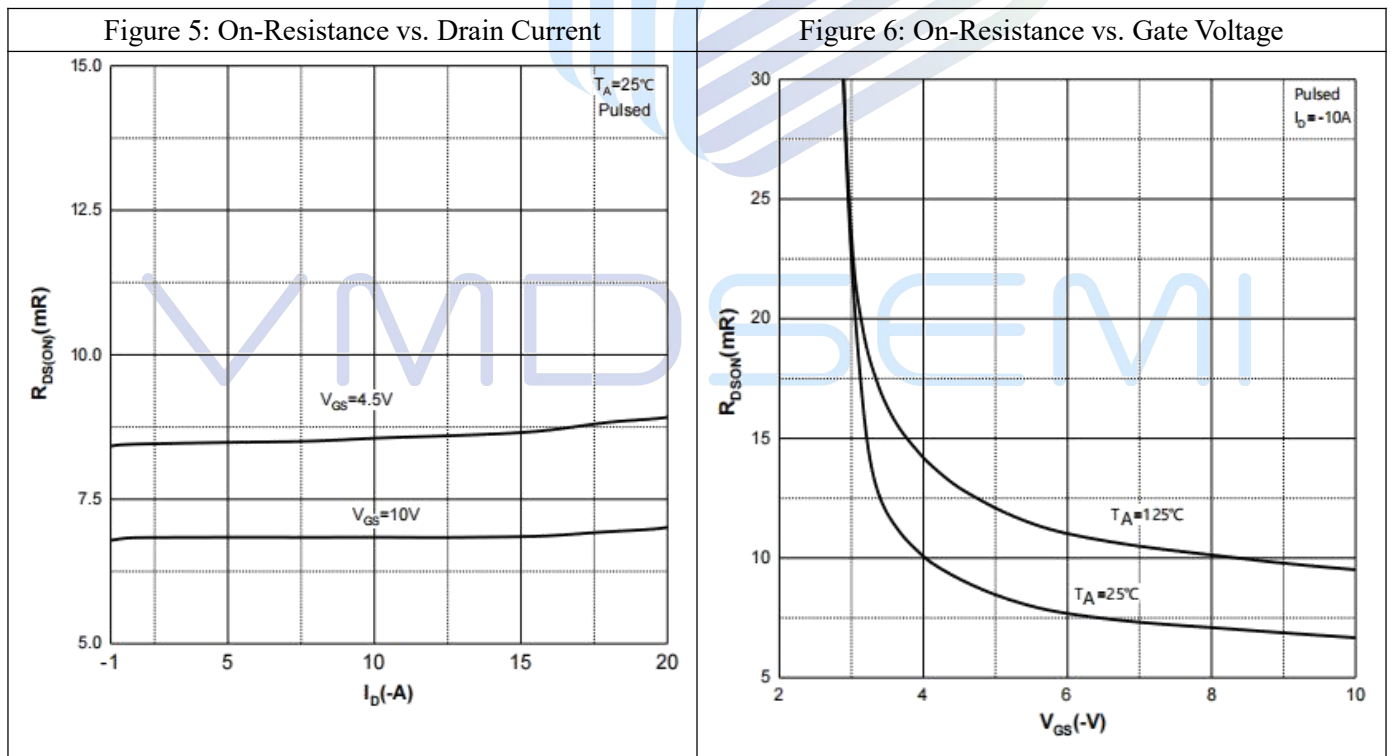
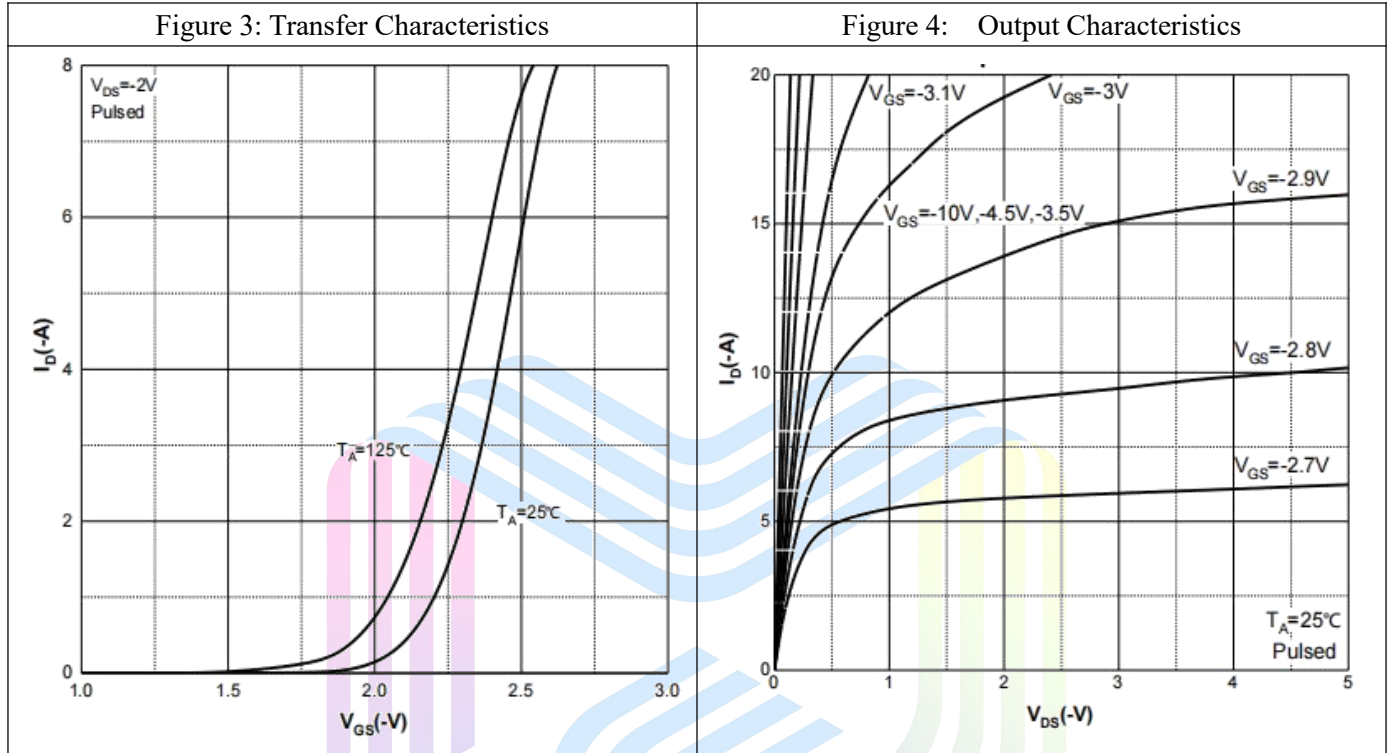


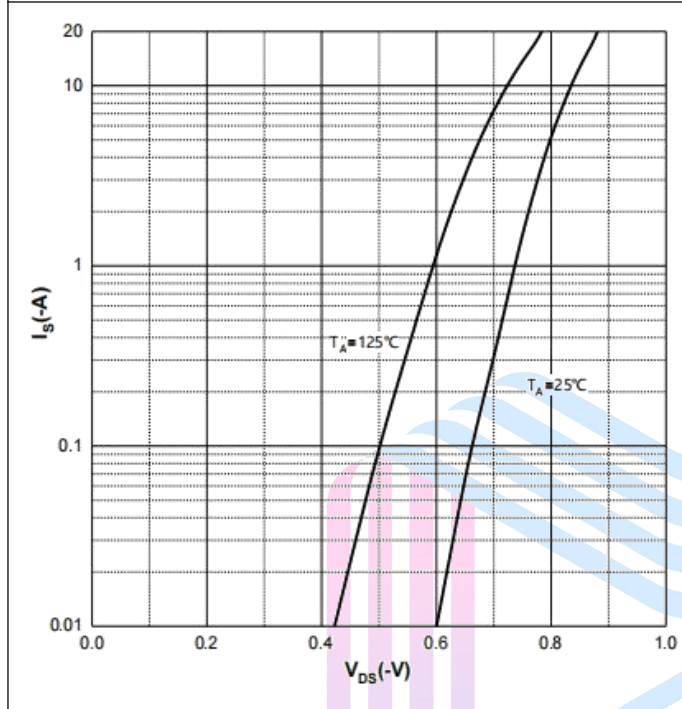
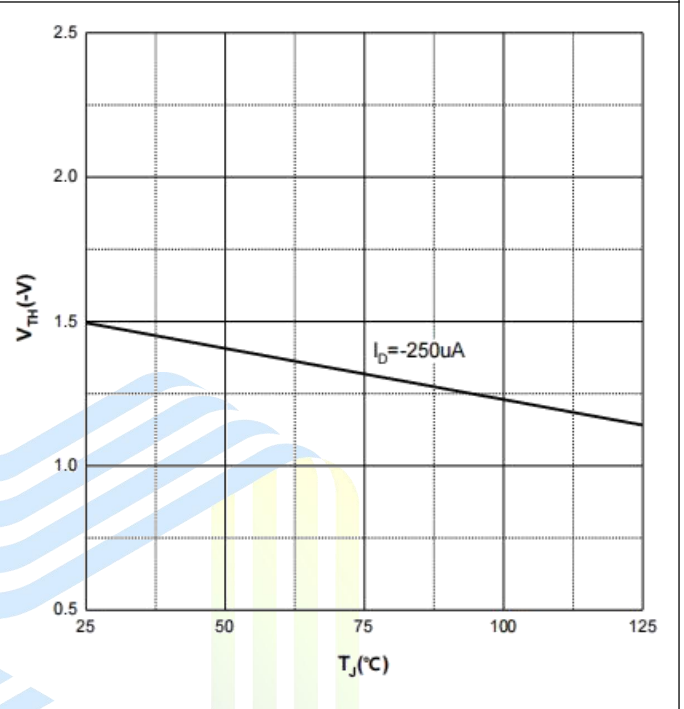
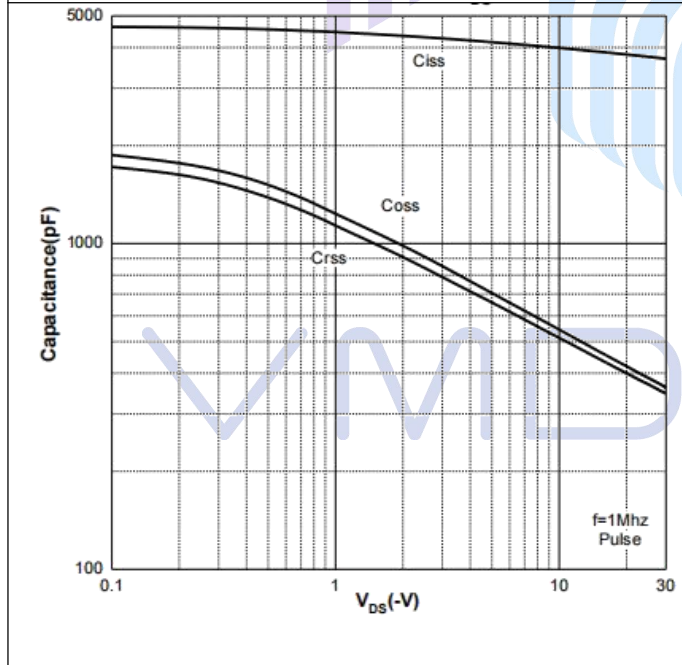
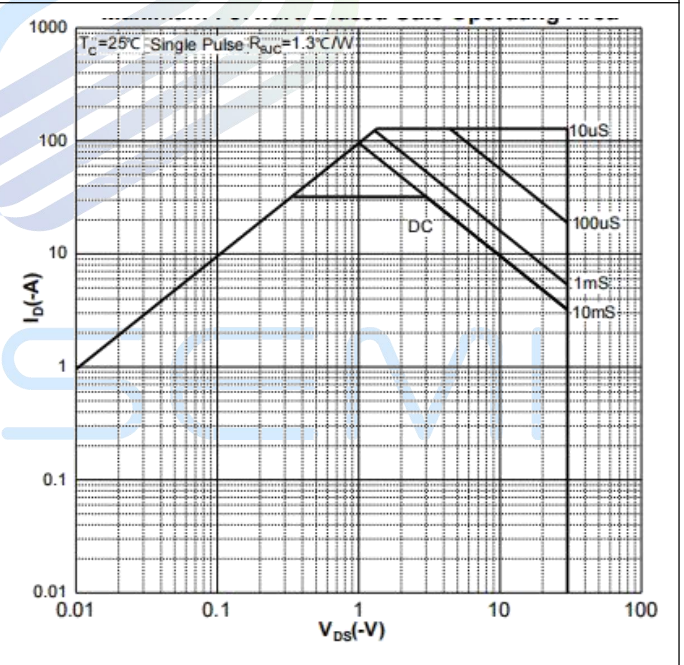
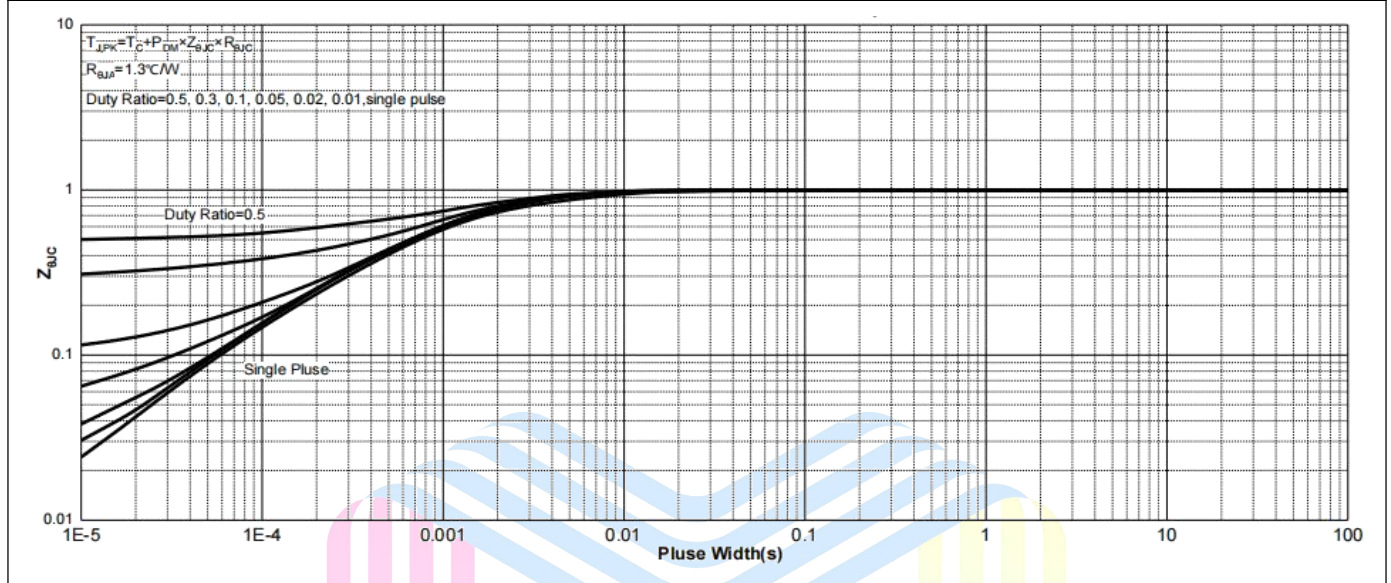
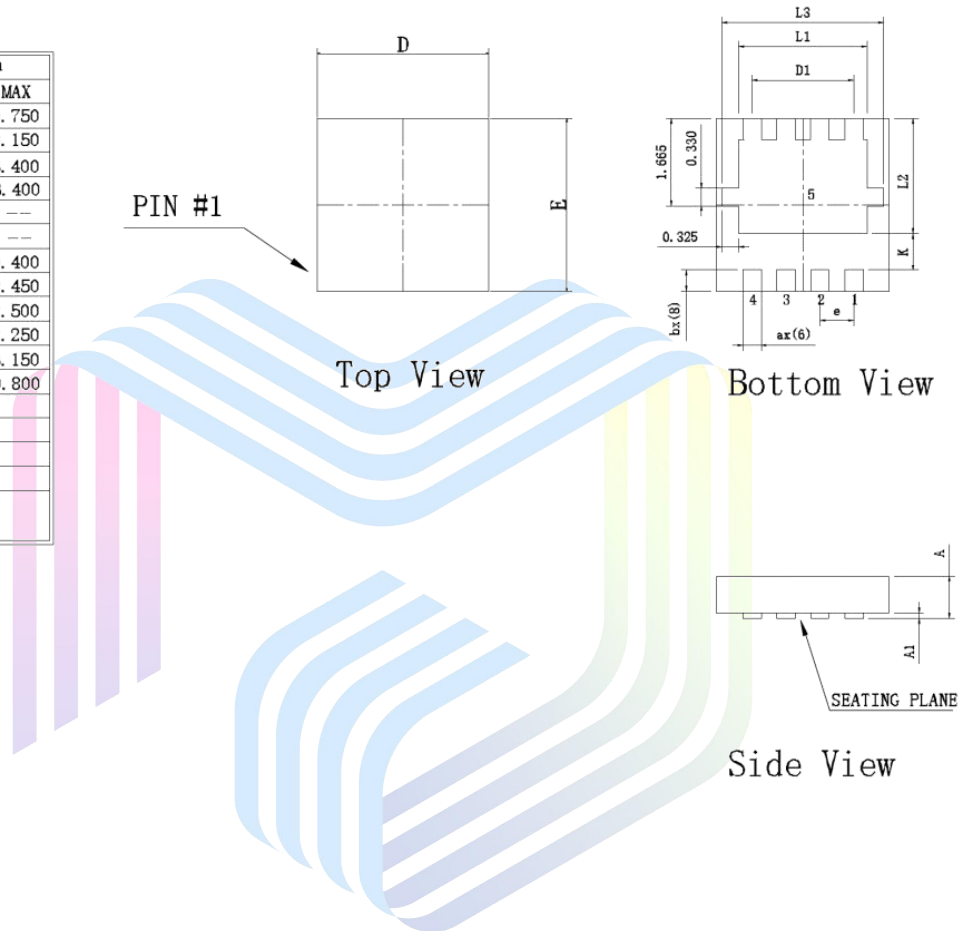
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance


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Mechanical Dimensions:
DFN3.3X3.3-8L Package Information

symbol	Dimension in mm		
	MIN	NOM	MAX
A	0.650	0.700	0.750
A1	0.050	0.100	0.150
D	3.200	3.300	3.400
E	3.200	3.300	3.400
D1	---	1.950	---
e	---	0.650	---
ax(6)	0.300	0.350	0.400
bx(8)	0.350	0.400	0.450
L1	2.400	2.450	2.500
L2	2.150	2.200	2.250
L3	3.050	3.100	3.150
K	0.600	0.700	0.800



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